

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT11171ST-3.3#PBF		(Engineering Calculation)		SOT-223				
(printed on: 7/16/2011 12:18:12 PM)				TOTAL MASS (g):		0.1169704		
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT		
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002855	1000000	24407.89		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.062693	975000	535973.3		
		Iron (Fe)	7439-89-6	0.001543	24000	13191.37		
		Phosporus (P)	7723-14-0	1.90E-05	300	162.4343		
		Zinc (Zn)	7440-66-6	4.50E-05	700	384.7128		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead Frame Total:				0.0643	1000000	549711.8
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.00160939	1000000	13758.95		
		External Plating Total:				0.00160939	1000000	13758.95
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	0.000514	1000000	4394.275		
		Internal Plating Total:				0.000514	1000000	4394.275
Die Attach	95 Pb / 5 Sn	Silver (Ag)	7440-22-4	0	0	0		
		Tin (Sn)	7440-31-5	7.70E-05	50000	658.2862		
		Lead (Pb)	7439-92-1	0.001466	950000	12533.09		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Antimony (Sb)	7440-36-0	0	0	0		
		Resin (EP)		0	0	0		
		Die Attach Total:				0.001543	1000000	13191.37
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004738	103000	40505.98		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.04117	895000	351969.4		
		Antimony	1309-64-4	0	0	0		
		Trioxide (Sb2O3)						
		Metal Hydroxid		0	0	0		
		Carbon Black (C)	1333-86-4	9.20E-05	2000	786.5239		
		Encapsulation Total:				0.046	1000000	393261.9
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000149	1000000	1273.827		
Estimated								
				TOTAL MASS (g):		0.1169704		